Specification of Thermoelectric Module

TETC1-12706

Description

The 127 couples, 40 mm × 40 mm size single module which is made of our high performance ingot to achieve superior cooling performance and 74°C or larger delta Tmax, is designed for superior cooling and heating applications. The module is able to run million thermal cycles in 70 °C temperature change range with less 3% degrading. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

Features

- High effective cooling and efficiency.
- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly, RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

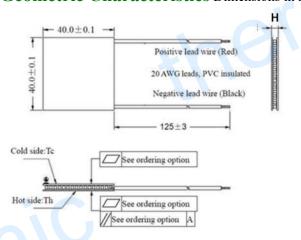
Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Temperature stabilizer
- Liquid cooling
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

_				
Th(°C)	27	90	Hot side temperature at environment: dry air, N ₂	
DT (9C)	74	100	Temperature Difference between cold and hot side of the module	
DT _{max} (°C)			when cooling capacity is zero at cold side	
U _{max} (Voltage)	16.8	20.3	Voltage applied to the module at DT _{max}	
I _{max(} amps)	6.3	6.3	DC current through the modules at DT _{max}	
Q _{Cmax} (Watts)	66	81.0	Cooling capacity at cold side of the module under DT=0 °C	
AC resistance(ohms)	2.05	2.45	The module resistance is tested under AC	
Tolerance (%)	± 10		For thermal and electricity parameters	

Geometric Characteristics Dimensions in millimeters



Ordering Option

Suffix	Thickness	Flatness/	Lead wire length(mm)		
	(mm)	Parallelism (mm)	Standard/Optional length		
TF	0:3.8±0.1	0:0.08/0.08	125±3/Specify		
TF	1:3.8±0.03	1:0.03/0.03	125±3/Specify		
Eg. TF01: Thickness 3.8±0.1(mm) and Flatness 0.03/0.03(mm)					

Manufacturing Options

A. Solder:

B. Sealant:

1. T100: BiSn (Tmelt=138°C)

1. NS: No sealing (Standard)

2. T200: CuAgSn (Tmelt = 217°C)

2. SS: Silicone sealant

3. T240: SbSn (Tmelt = 240° C)

3. EPS: Epoxy sealant

C. Ceramics:

D. Ceramics Surface Options:

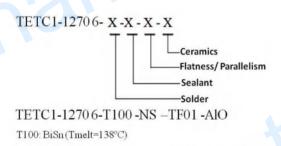
1. Alumina (Al₂O₃, white 96%)

1. Blank ceramics (not metalized)

2. Aluminum Nitride (AlN)

2. Metalized

Naming for the Module

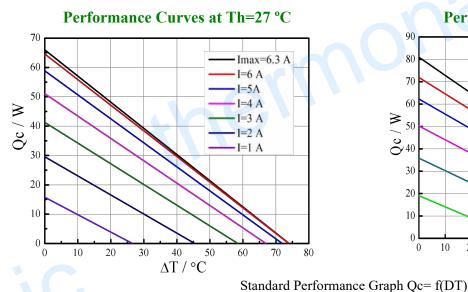


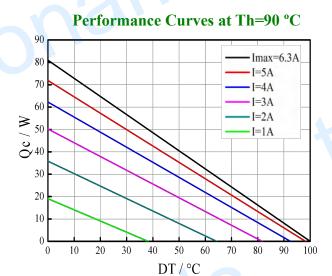
NS: No sealing AlO: Alumina (Al2O3, white 96%)

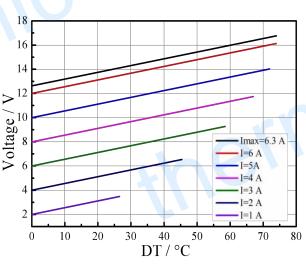
Operation Cautions

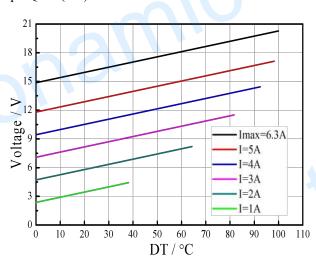
- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I_{max} or V_{max}
- Work under DC

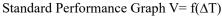
Performance Curve

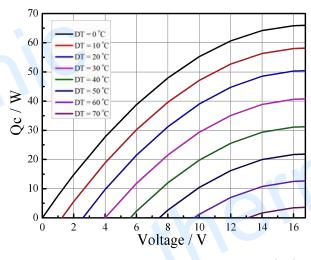


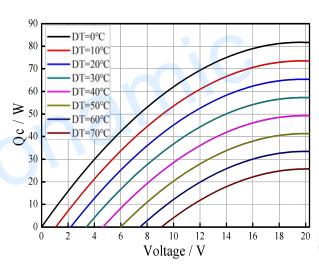




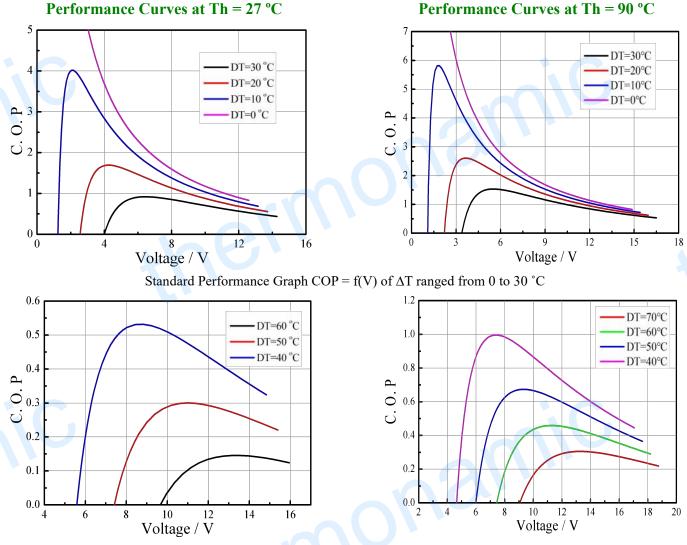








Standard Performance Graph Qc = f(V)

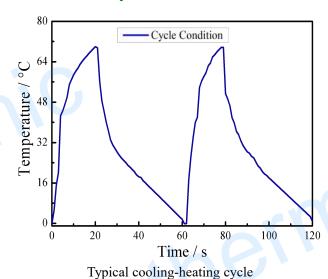


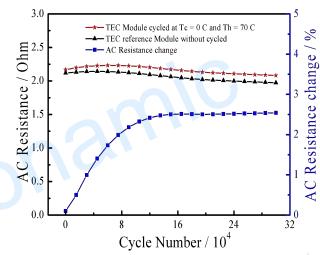
Standard Performance Graph COP = f(V) of ΔT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V × I).

A typical 127 couples module is fabricated by the unique "soft" process and has demonstrated that it only has 2.5% degrading after 300,000 thermal cycling. The below graphic shows that in beginning 120,000 cycles, it degrade about 2.5%, and then go on stable with very tiny degrading in further 180,000 thermal cycles. It is derived out that the modules can go over million thermal cycles.

TEC Thermal Cycle Lifetime Test





The Chart for AC Resistance and AC Resistance Changes vs. Cycle Number